

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	THERMALLY ENHANCED STACKED DIE PACKAGE AND FABRICATION METHOD		
Application Type: regular, utility			
Attorney Docket Number: 27-017			
Correspondence address:			
Customer Number:		22898	*22898*
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Publication Information:

Suggested Figure for Publication – FIG 4

Suggested Classification –

Suggested Technology Center –

Total Number of Drawing Sheets – 4

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